TOSHIBA BIPOLAR DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

# TD62306P,TD62306F

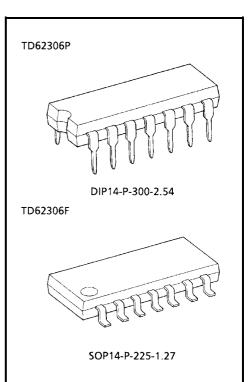
#### 6CH LOW SATURATION SINK DRIVER

The TD62306P, TD62306F are comprised of six NPN low saturation drivers.

All units feature integral clamp diodes for switching inductive loads and protective diodes against a negative input voltage. Applications include relay, hammer, lamp and LED driver.

#### FEATURES

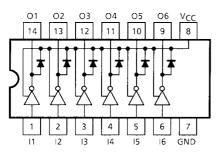
- Low saturation output voltage : V<sub>CE</sub> (sat) = 0.6 V (Max.) @IOUT = 120 mA
- Output rating (single output) 20 V (Min.) / 150 mA (Max.)
- Inputs compatible with 5~15 V PMOS, CMOS
- Input protective diodes against a negative input voltage
- Package type-P : DIP-14 pin
- Package type-F : SOP-14 pin



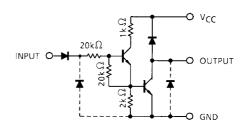
Weight

DIP14-P-300-2.54 : 1.11 g (Typ.) SOP14-P-225-1.27 : 0.16 g (Typ.)

#### PIN CONNECTION (TOP VIEW)



#### SCHEMATICS (EACH DRIVER)



Note: The input and output parasitic diodes cannot be used as clamp diodes.

#### MAXIMUM RATINGS (Ta = 25°C)

CHARACTERIS	SYMBOL	RATING	UNIT		
Supply Voltage	V <sub>CC</sub>	-0.5~20	V		
Output Sustaining Voltage	V <sub>CE (SUS)</sub>	-0.5~V <sub>CC</sub> + 0.5	V		
Output Current	IOUT	150	mA / ch		
Input Voltage	V <sub>IN</sub>	-37~20	V		
Input Current	I <sub>IN</sub>	1.5	mA		
Clamp Diode Reverse Volta	V <sub>R</sub>	20	V		
Clamp Diode Forward Curre	١ <sub>F</sub>	120	mA		
Dower Dissinction	Р	D-	1.0	W	
Power Dissipation	F	PD	0.625 (Note)	vv	
Operating Temperature	Р	<b>т</b>	-30~75	°C	
	F	T <sub>opr</sub>	-40~85	U	
Storage Temperature	T <sub>stg</sub>	-55~150	°C		

Note: On Glass Epoxy PCB (50 × 50 × 1.6 mm Cu 30%)

#### **RECOMMENDED OPERATING CONDITIONS** (Ta = -40~85°C for Type-F and Ta = -30~75°C for Type-P)

CHARACTERISTIC		SYMBOL	CONDITION	MIN	TYP.	MAX	UNIT	
Supply Voltage		V <sub>CC</sub>	_	4.75	_	18	V	
Output Current		IOUT	DC 1 Circuit	0	_	120		
			T <sub>pw</sub> = 25 ms, Duty = 10% 6 Circuits	0	_	100	mA / ch	
Input Voltage		V <sub>IN</sub>	_	-35	_	V <sub>CC</sub>	V	
Clamp Diode Reverse Voltage		V <sub>R</sub>	_	_	_	18	V	
Clamp Diode Forward Current		١ <sub>F</sub>	_	_	_	120	mA	
Power Dissipation	Р	Po	—	_	_	0.44	w	
	F	PD	(Note)		_	0.325	vv	

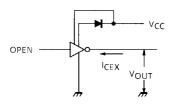
Note: On Glass Epoxy PCB (50 × 50 × 1.6 mm Cu 30%)

## ELECTRICAL CHARACTERISTICS (Ta = 25°C)

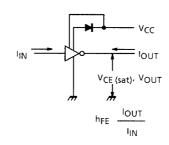
CHARACTERISTIC		SYMBOL	TEST CIR- CUIT	TEST CONDITION		MIN	TYP.	MAX	UNIT	
Output Leakage Curr	Curront	Р	- I <sub>CEX</sub>	1	V <sub>CC</sub> = 18 V V <sub>OUT</sub> = 18 V	Ta = 75°C	_	_	100	μA
	Juneni	F				Ta = 85°C	—	_	100	
Output Saturation Voltage		V <sub>CE (sat)</sub>	2	V <sub>CC</sub> = 5 V, I <sub>IN</sub> = 0.2 mA I <sub>OUT</sub> = 120 mA		-	0.45	0.6	V	
DC Forward Current Transfer Ratio		h <sub>FE</sub>	2	V <sub>CC</sub> = 5 V, V <sub>OUT</sub> = 2 V I <sub>OUT</sub> = 120 mA		1000	_	_	_	
Input Current	Outou	Output On	I <sub>IN (ON)</sub>	3	V <sub>IN</sub> = 5 V, I <sub>OUT</sub> = 120 mA		_	0.16	0.23	mA
	Outpu				V <sub>IN</sub> = 15 V, I <sub>OUT</sub> = 120 mA		_	0.66	0.94	
	Output Off		I <sub>IN (OFF)</sub>	4	V <sub>IN</sub> = -35 V		_	-	-10	μA
Clamp Diode Forward Voltage		VF	5	I <sub>F</sub> = 120 mA		_	1.25	1.6	V	
Supply Current	Outpu	it On	ICC (ON)	6	$V_{CC} = V_{IN} = 5 V$		_	4.0	6.0	mA /
	Outpu				V <sub>CC</sub> = V <sub>IN</sub> = 15 V		_	14.0	22	Gate
	Outpu	ıt Off	I <sub>CC (OFF)</sub>	6	V <sub>CC</sub> = 18 V, V <sub>IN</sub> = 0 V		—	_	10	μA
Turn-On Delay		t <sub>ON</sub>	7	V <sub>CC</sub> = 18 V, R <sub>L</sub> = 150 Ω C <sub>L</sub> = 15 pF		_	0.1	_	μs	
Turn-Off Delay		t <sub>OFF</sub>	'			_	0.8	_	μs	

## **TEST CIRCUIT**

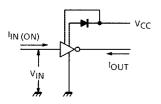
1. ICEX

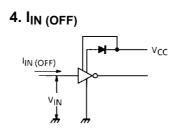


# 2. h<sub>FE</sub>, V<sub>CE (sat)</sub>



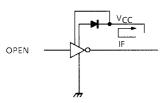
3. I<sub>IN (ON)</sub>

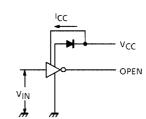




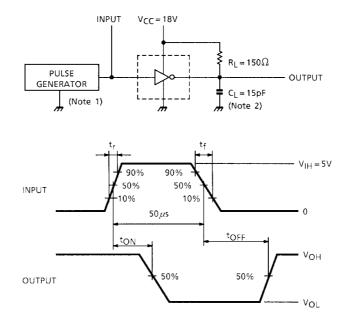
5. V<sub>F</sub>







#### 7. t<sub>ON</sub>, t<sub>OFF</sub>



Note 1: Pulse Width 50  $\mu$ s, Duty Cycle 10% Output Impedance 50  $\Omega$ , t<sub>f</sub> ≤ 5 ns, t<sub>f</sub> ≤ 10 ns Note 2: C<sub>L</sub> includes probe and jig capacitance

#### **PRECAUTIONS for USING**

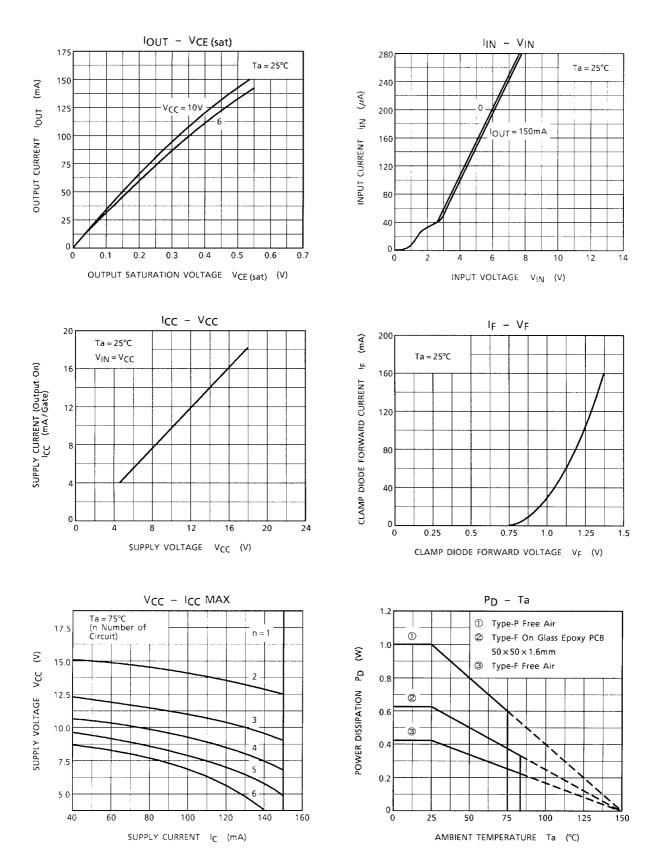
This IC does not include built-in protection circuits for excess current or overvoltage.

If this IC is subjected to excess current or overvoltage, it may be destroyed.

Hence, the utmost care must be taken when systems which incorporate this IC are designed.

Utmost care is necessary in the design of the output line,  $V_{CC}$  and GND line since IC may be destroyed due to short-circuit between outputs, air contamination fault, or fault by improper grounding.

# **TOSHIBA**

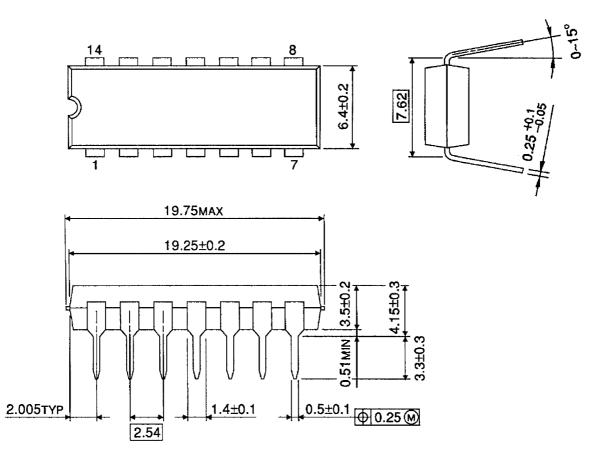


# **TOSHIBA**

## PACKAGE DIMENSIONS

DIP14-P-300-2.54A

Unit: mm



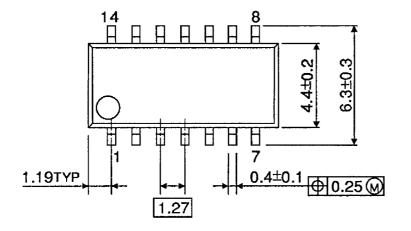
Weight: 1.11 g (Typ.)

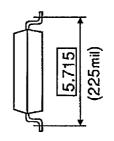
# TOSHIBA

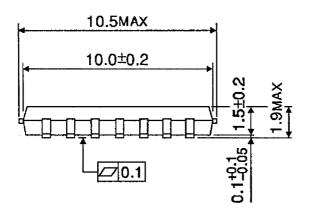
## TD62306P/F

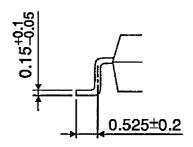
#### PACKAGE DIMENSIONS

SOP14-P-225-1.27









Weight: 0.16 g (Typ.)

Unit: mm

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